

GENE-BT05

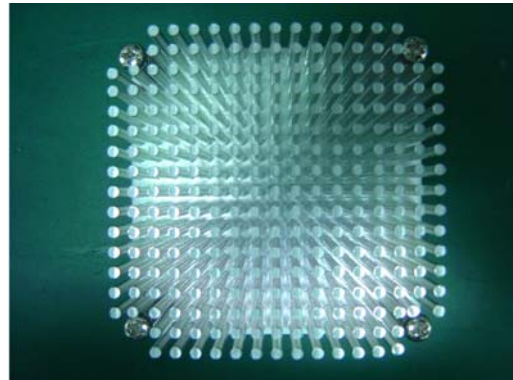
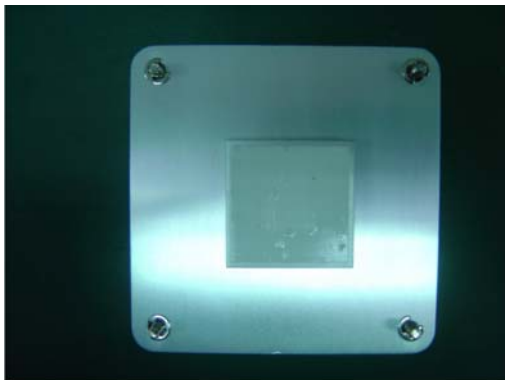
Thermal Image Analysis Report

Summary	<input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation Comment: <u>After compared with component datasheet, there were 3 components' surface temperature located in marginal pass criteria.</u>			
	Test Result Summary			
	Critical	Major	Minor	Enhancement
Defect Found	0	0	0	3
Defect Unsolved	0	0	0	3

Issue date	Approval	Test Engineer
2014 / 06 / 26	Tom Lin	Juno Cheng

Sample Configuration & Quantity Under Test

- Model name : GENE-BT05 A0.3
- CPU Board : GENE-BT50 A0.2
- CPU : Intel Celeron Processor J1900 (2M Cache, up to 2.42 GHz)
- Memory : DSL DDR3L 1600 4GB / PROMOS V73CBG04808RAJJ11
- 2.5" SATA HDD : WD WD3200BEVT 2.5" 320GB
- BIOS : GENE-BT05 M/D (GBT5BT03)(05/12/2014)
- Test Software : Windows 7 / Run PassMark Burn In Test 7.1 Pro
- Power : AT Power
- Heatsink :



Thermal Image Analysis

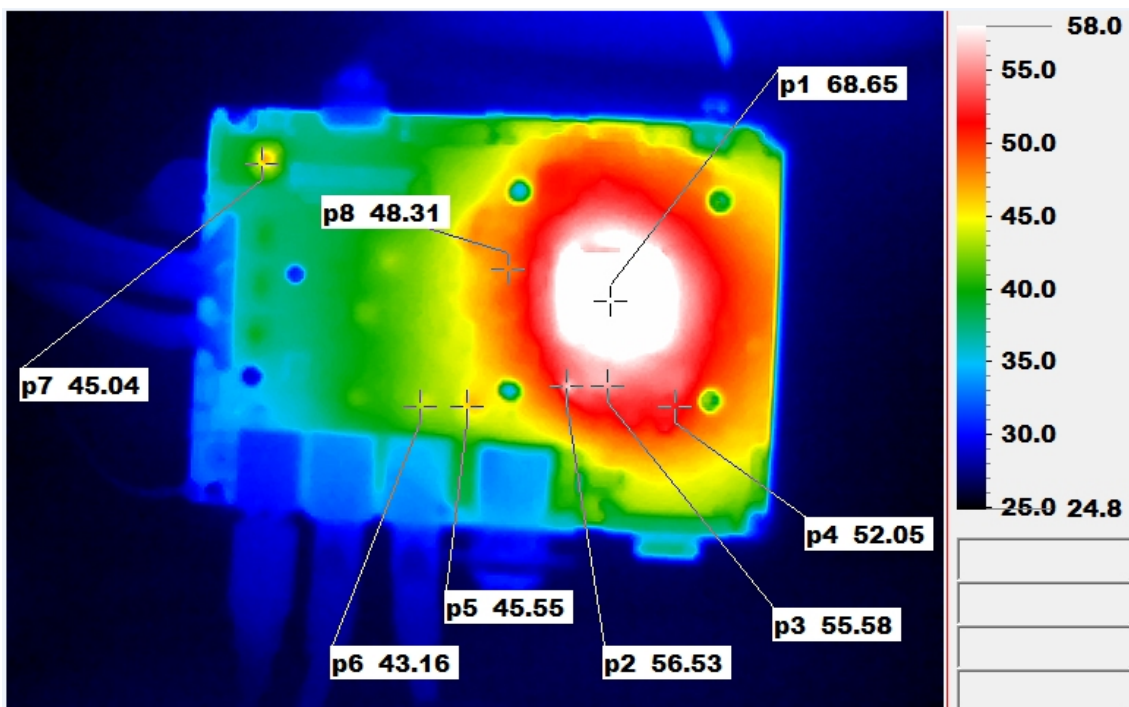
1. Test Date: 2014-06-26
2. Test Product: GENE-BT05
3. Test Site: AAEON QE Dept.
4. Temperature Measurement:
 - 4.1. 40 Channel Thermal Recorder:
 - 4.1.1 YOKOGAWA Inc,
 - 4.2.2 Model: DA100-13-1D
 Date of Calibration: 2013/10/01
 Serial Number: 12A323190
 - 4.2. IR Scanner: Infrared Camera
 - 4.2.1 NEC Avio Infrared Technologies Co., Ltd.
 - 4.2.2 Model: Thermo GEAR G100W2-D
 Date of Calibration: 2013/12/30
 Serial Number: 1051444
5. Test Condition:

Test by DA-100: 25.0°C with Heat Sink + FAN (Full speed)
6. Take Picture Time:

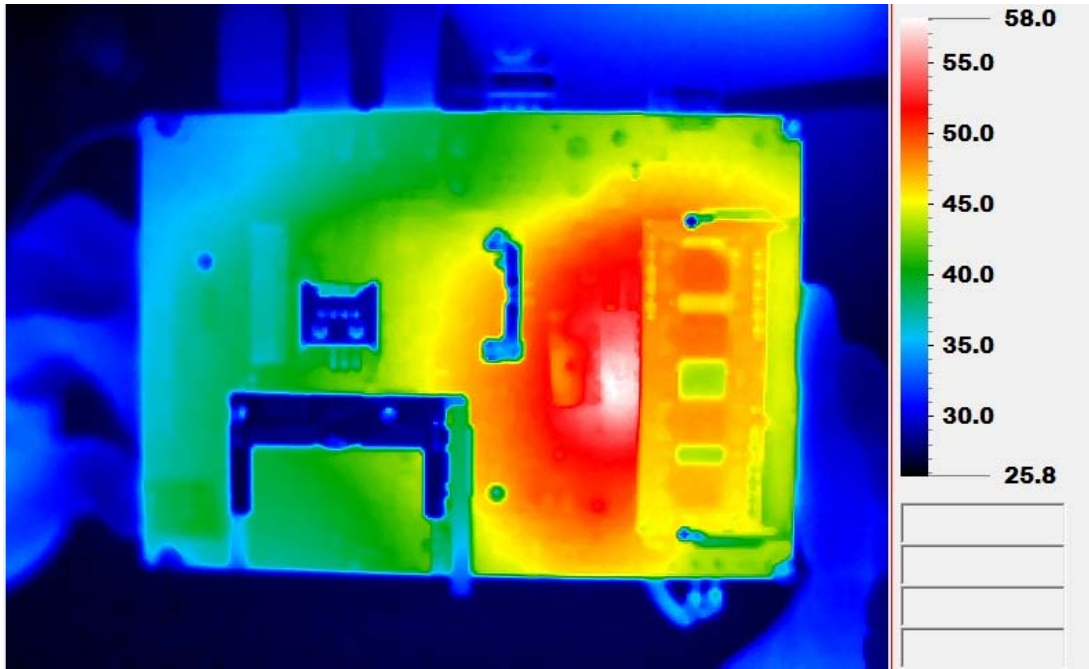
After power on 2 hours

Temperature Profile Test:

Component Side:

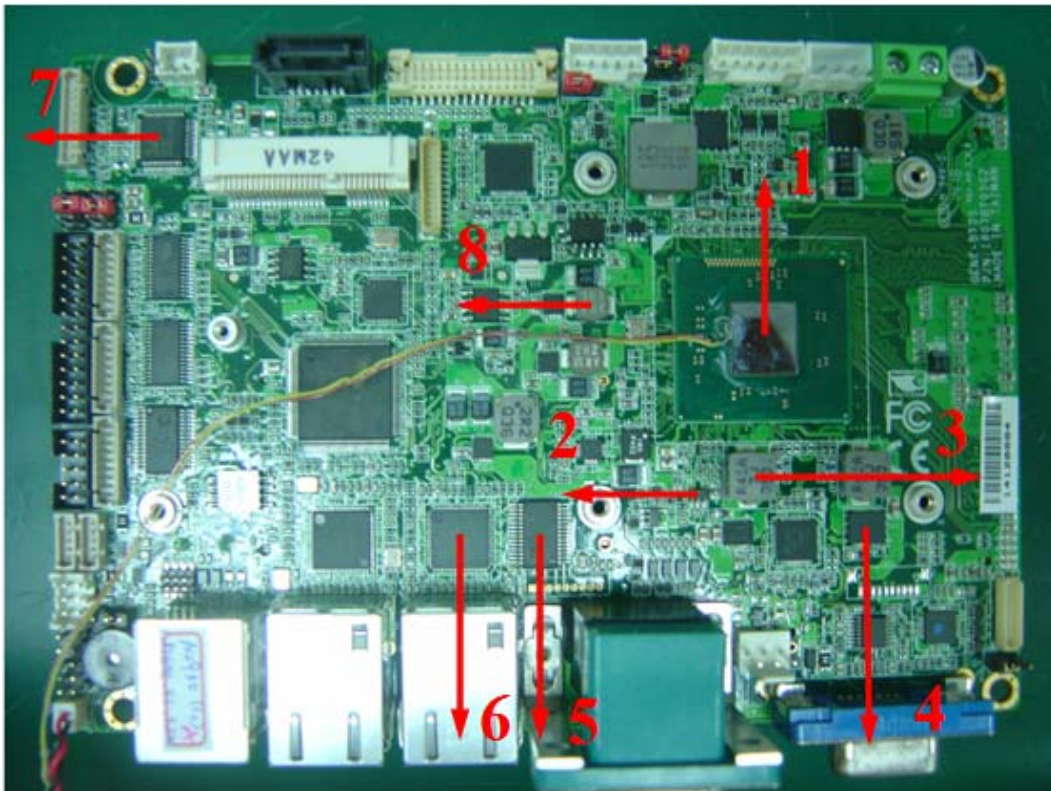


Back Side



Terminal Recorder :

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

Point	Position	Describe	Tc (*1) (°C)	Tm (*2) Measured Under		Note
				25.0°C	60°C	
1	U16	Bay Trail N2930	105	54.4	89.4	
2	U26	UP0107BMA5-00	100	52.1	87.1	
3	L7	Panasonic.ETQP4LR42AFM	130	59.8	94.8	
4	Q15	NTMFD4901NFT1G	100	52.6	87.6	
5	U24	ADM213EARSZ	100	49.2	84.2	
6	U21	Intel i211AT	85	46.8	81.8	Note3
7	U5	ALC892-CG	100.5	48.3	83.3	
8	L3	MPLCG0530L3R3	135	52.4	87.4	
9	CN31	Battery CR2032-HAT00	70	26.9	61.9	Note3
10		Memory chipset	95	53.2	88.2	Note3

Note(*):

- "Tc" indicates the component's case maximum temperature value specified in its datasheet.
- "Tm" indicates the measured Tc value under working environmental temperature within product specification.
- Judgment Criteria:**
 - Fail** : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
 - Margin** : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
 - Pass** : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.
- Defect NO** : [E130607QEE34](#)